

**Amendments to the Specification:**

Please replace the paragraph bridging pages 7 and 8 with the following amended paragraph:

The module shown in Figure 2 has a plurality of interface pins IPI-1, IPI-2, IPI-3...IPI-N and a plurality of integrated circuit devices mounted inside the package. Each integrated circuit package device 11' has a plurality of interface ports IPO-1, IPO-2, IPO-3...IPO-N, at least one interface port IPO-1 being connected to another one of the plurality of integrated circuit devices 11'. At least one of the integrated circuit devices 11' has an interface port IPO-4 connected to an interface pin IPI and at least one of the integrated circuit devices 11' is packaged in a chip scale package. As illustrated in Figure 2, the primary communications between the onboard integrated circuit chips 11' and the interface pins IPI for the package TIM' are designated by the connection lines 75 between the onboard integrated circuit chips 11 and the interface ~~pins IPP~~ pins IPI. The secondary arrows SA represent secondary or intermediate communications between the onboard integrated circuit chips 11' and through the interface ports designated by the lines IPO. Note in particular that in this embodiment, the interface pins IPI connected to the onboard integrated circuits are significantly fewer than the intermediate communications or secondary communications between the onboard integrated circuit 11' and through the interface ports IPO.